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U.S. Department of Commerce Patent and Trademark Office

Attorney's Docket No. 06618-720001

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**Applicant** Eui-Hyeok Yang and Dean V. Wiberg

Filing Date November 2, 2001 Group Art Unit 2812

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	Substitute Disclosure Form (PTO-1449)

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Substitute Form PTO-1449 (Modified)	U.S. Department of Commerce Patent and Traderitary Office	Attorney's Docket No. 06618-720001	Application No. 10/005,765
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Applicant

Eui-Hyeok Yang and Dean V. Wiberg

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